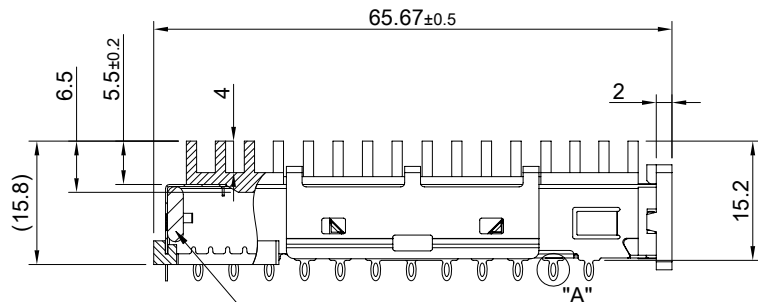
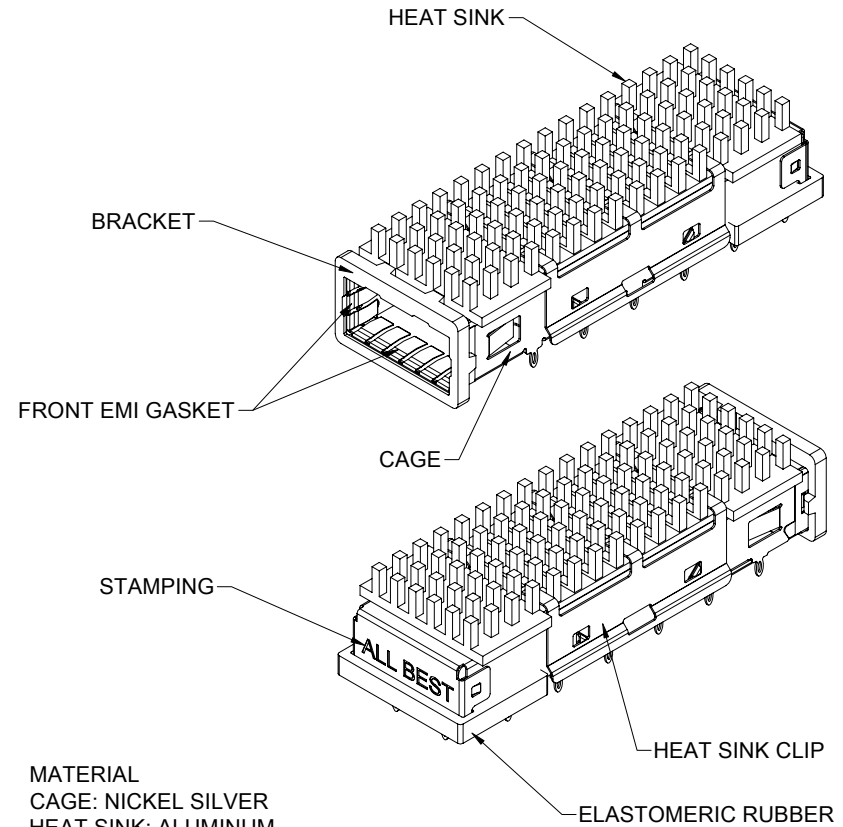
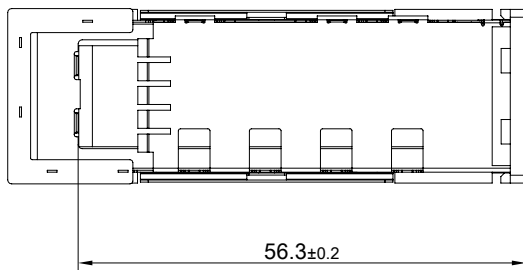
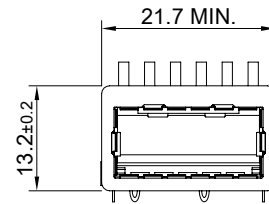


DETAIL A
SCALE 5:1





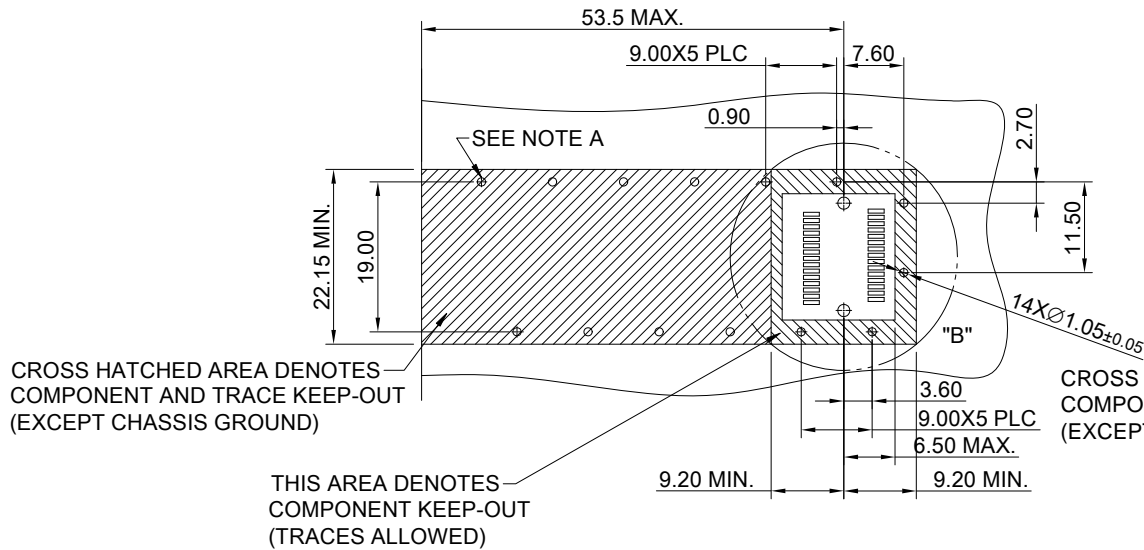
REAR EMI GASKET



MATERIAL
 CAGE: NICKEL SILVER
 HEAT SINK: ALUMINUM
 HEAT SINK CLIP: STAINLESS STEEL
 FRONT EMI GASKET: COPPER ALLOY
 REAR EMI GASKET: CONDUCTIVE FOAM
 ELASTOMERIC RUBBER: CONDUCTIVE RUBBER
 BRACKET: ZINC ALLOY

FINISH
 HEAT SINK: ANODE PROCESS
 FRONT EMI GASKET: TIN OVER COPPER
 BRACKET: TIN

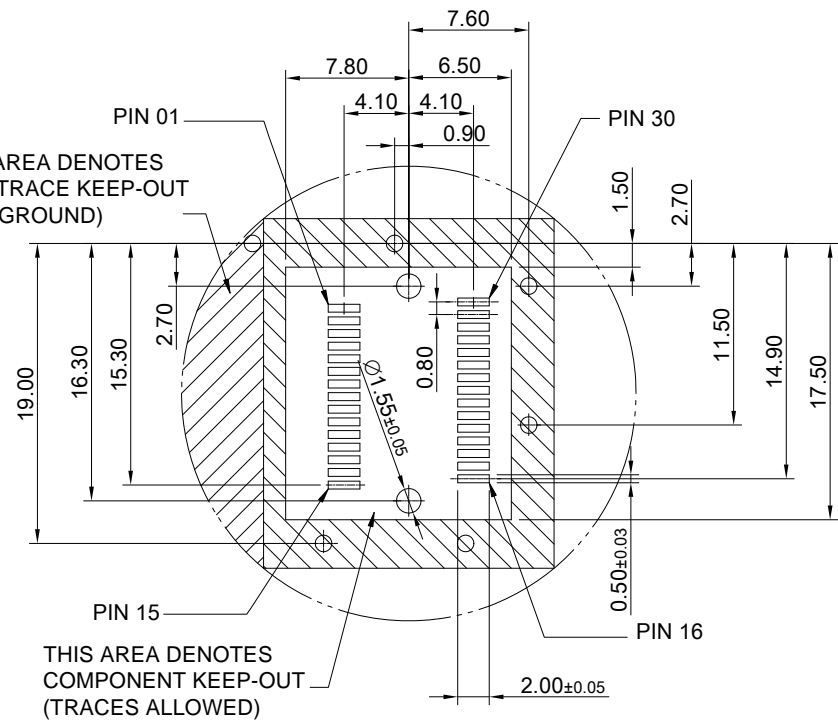
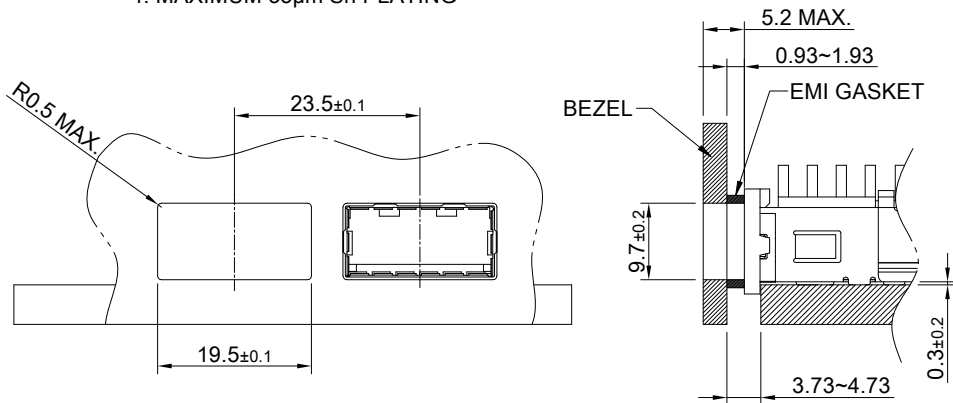
 ALL BEST ELECTRONICS CO., LTD.	TITLE: XFP Cage Assembly With Heat Sink 6.5mm Tall		SHEET: 1/2	REV. I
	DWG#: R-CG-008030-11		CHECKED: Gary Kang	
	UNIT: mm	SCALE: A4 1:1	FINISH:	APPROVED: George Yang
	 THIRD ANGLE PROJECTION TOLERANCE: Angle: ± 1° X ± 0.25 .X ± 0.2 .XX ± 0.15		MATERIAL: RoHS Compliant	DATE: 09/10/2019
		DRAWN: Yilu		



DETAILED HOST BOARD MECHANICAL LAYOUT
TOLERANCE: \pm 0.05

NOTE A: RECOMMENDATION FOR P.C.B. HOLES

1. HOLE \varnothing AFTER DRILLING: 1.15 \pm 0.02
2. HOLE \varnothing AFTER TIN LEAD PLATED: 1.05 \pm 0.05
3. 25 μ m-50 μ m COPPER UNDERPLATED
4. MAXIMUM 35 μ m Sn PLATING



DETAILED HOST BOARD MECHANICAL LAYOUT
TOLERANCE: \pm 0.05

DETAIL B
SCALE 2:1



ALL BEST ELECTRONICS CO., LTD.

TITLE: XFP Cage Assembly With Heat Sink 6.5mm Tall

DWG#: R-CG-008030-11

SHEET: 2/2
REV: I

UNIT: mm

SCALE: A4 1:1

FINISH:

CHECKED: Gary Kang

THIRD ANGLE PROJECTION

MATERIAL: RoHS Compliant

APPROVED: George Yang

TOLERANCE: Angle: \pm 1°
X \pm 0.15 .X \pm 0.1 .XX \pm 0.05

DRAWN: Yilu

DATE: 09/10/2019